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Procedure for the Electrical Contacting of Two Metal Structures

Summary

The present invention concerns a procedure for the electrical contacting of two metal structures, wherein at least one of the metal structures is provided on its side facing the second metal structure with a bonding zone protruding from a plane, wherein an electrically insulating layer is arranged between the metal structures, wherein one metal structure is laminated to the electrically insulating layer and the second metal structure is laminated to the electrically insulating layer subsequently or simultaneously, and wherein the two metal structures are electrically contacted while the lamination of the second metal structure to the electrically insulating layer is ongoing.

FIGS 1-3